

Francis Gold Sy

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EDUCATION

City University of New York, City College

Expected Grad: *June 2022*

Major: B.E., Mechanical Engineering; Minor: Computer Science

GPA: 3.86

S Jay Levy Fellow: a year-long professional development experience culminating in a summer internship

Relevant Coursework: Engineering Materials, Mechatronics, Fluid Mechanics, Thermodynamics

PROFESSIONAL SKILLS

Software: SolidWorks, Autodesk Fusion 360, MeshMixer, Matlab, Java, Arduino, Microsoft Office

Manufacturing: FDM & SLA 3D Printers, Laser Cutter, Prototyping

Languages: English (Fluent), Tagalog (Native)

EXPERIENCE

WearWorks Inc, NYC

June 2020 – Aug 2020

Mechanical Engineering Intern

- Collaborated in a team of three to design, iterate, and prototype the WayBand for manufacturing
- Conducted injection molding and stress simulations in SolidWorks to optimize product for manufacturing
- Managed DFMEA, PFMEA, process flow chart, and other manufacturing-related documents
- Contacted and identified promising U.S. and overseas suppliers for B.O.M. needs
- Ideated and modeled different versions of packaging for company product

Zahn Innovation Center, CCNY

Feb 2019 – May 2020

Engineering Apprentice

- Using SolidWorks, Fusion 360, 3D printers, and laser cutter for various projects and design applications
- Executed design of various client-requested products through small team collaboration
- Experienced in the use and maintenance of FDM and SLA 3D printers
- Designed, iterated, and delivered a multi-accessory K-8 mathematical learning apparatus to an outside client

WearWorks Inc, NYC

Jan 2020 – Feb 2020

Product Engineering Intern

- Lead development and production of the WayBand for showcasing events and product launch
- Soldered, assembled, and applied finishing techniques for WayBand production
- Operated and maintained the Form 2 to lead product iterations and development

DogSpot Inc, NYC

June 2019 – Aug 2019

Engineering Intern

- Supported circuit board production through wire prep, soldering, and board assembly
- Managed circuit board materials; documented assembly and troubleshooting processes
- Helped streamline process in building and shipping commercial products
- Maintained strong communication with assembly team to ensure deadline completion and smooth workflow

Tech Achievement Institute, NYC

May 2018 – May 2019

Lead Arduino/Robotics Instructor

- Organized and introduced a robotics curriculum through Arduino platform
- Aided students as young as 8 years old in creating LED, sensor, and motorized car projects

PROJECTS

Customized PCB Keychains

August 2019

- Used Autodesk Fusion 360 to create a two-part keychain casing using a snap-fit mechanism; included company logo on front and font-customized names on the back
- Soldered LEDs, wires, battery mount, and button onto circuit boards; installed boards into 3D printed casing

ACCOMPLISHMENTS

- March 2019: Mark Zemansky Introductory Physics Prize Winner
- January 2018: FIRST Tech Challenge Inspire Award recipient